

ABSTRACT

ROTATIONAL SLURRY DISTRIBUTION SYSTEM FOR ROTARY CMP SYSTEM

An apparatus for slurry distribution during semiconductor wafer polishing operations. The slurry is gravity fed or fed under pressure and broadcast under an angle across the entire face of the polishing pad by either a rotating a rotating slurry nozzle arrangement or by a rotating slurry shaft arrangement. This as opposed to the conventional slurry supply lines, which are stationary in design.

(FIGURE 2 IS SUGGESTED FOR PUBLICATION)